



Embedded Power Management for Automotive Microcontroller Units (MCUs) and its Challenges

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Infineon μ C Automotive Applications

2

Power Managements: Evolution

3

Power Management: Present Development

4

Power Management: Challenges

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Power Management: Challenges

Infineon μ C Automotive Applications

Strategy: Chassis, Safety and ADAS/ Connectivity



Chassis, Motor Control



Safety



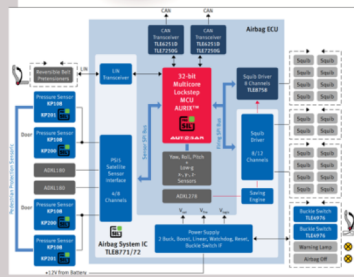
Car Communication

Airbag ECU Overview

➤ **Scope for μ C:** central airbag ECU

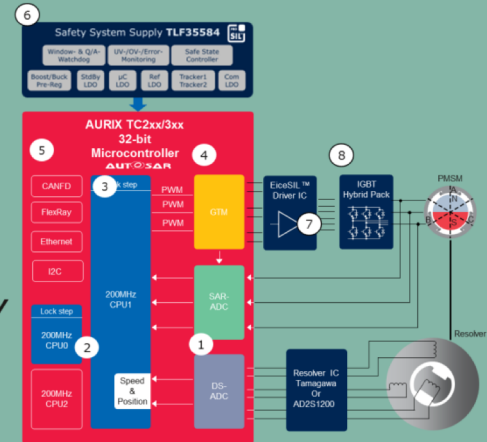
➤ **Airbag tasks:**

- **Evaluate** information from crash sensors and decide to trigger the squibs for bags, belts, pedals, battery, etc;
- **Crash** data recording (LV37):
- **Emergency** call
- **Ensure** power supply during and short after an event (crash) is a key element of airbag applications



Hybrid Electric Vehicle (H)EV Inverter

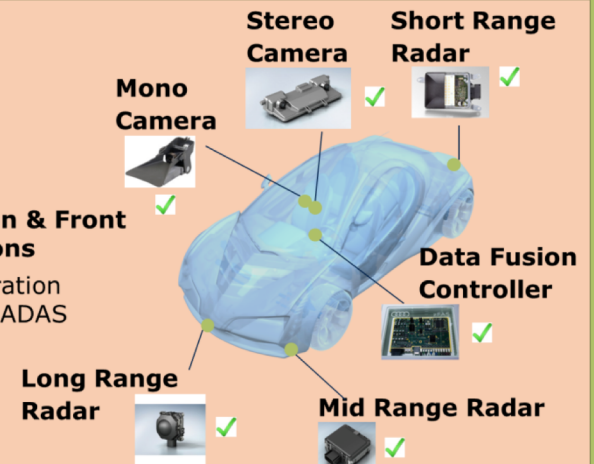
- 1 **DS-ADC (resolver)**
Motor position sensing
- 2 **Triple core**
Real time app.
- 3 **Safety, ISO26262**
Lock step, IOM...
- 4 **GTM timer**
Motor control & tuning
- 5 **CAN FD**
Fast communication
- 6 **Single voltage supply**
Incl. safety features
- 7 **EICE SIL driver:**
Safety function
- 8 **next IGBT module:**
Efficiency \downarrow 30%



Advanced Driving-Assistance System; ADAS;

➤ **Radar, Data Fusion & Front Camera applications**

- AURIX™ 2nd generation portfolio supports ADAS applications



Infineon μ C Automotive Applications

SoC Power Management System (PMS) constraints



Performance &
Power Reduction



PMS Performance providing supply for up to 6 main cores

Scalability and
Backward
Compatibility



PMS Concepts supporting backward compatibility (HW/SW reuse)

Functional Safety



PMS Concepts following **ISO26262** standard, enabling **ASIL-D** level

Security



PMS Concepts supporting security functions,

Networking



PMS supporting peripherals to address the growing demands of **in-vehicle networking**

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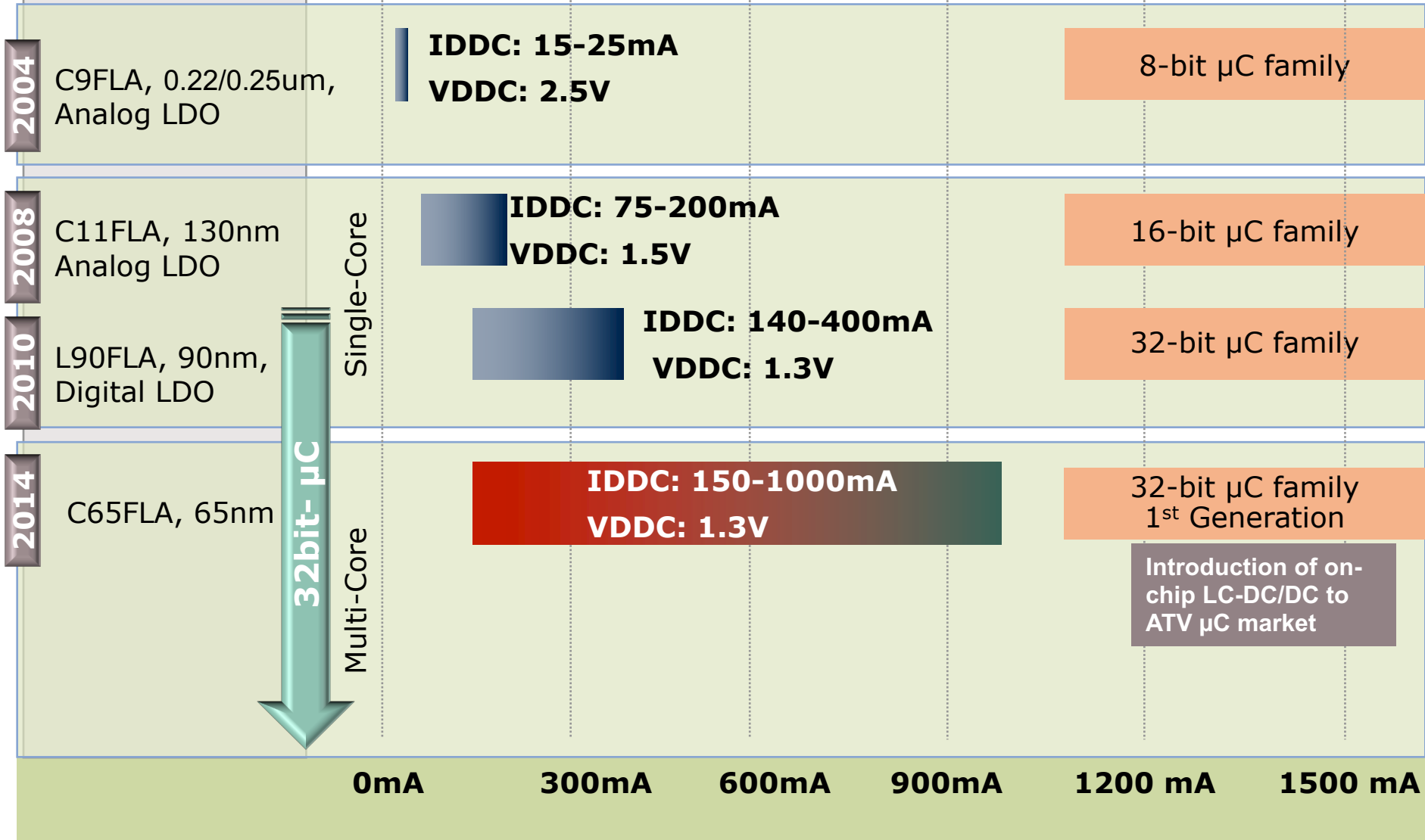
Power Management: Challenges

IFX Automotive Microcontroller

VR Architecture & Supply Current Demand



Embedded Flash Automotive



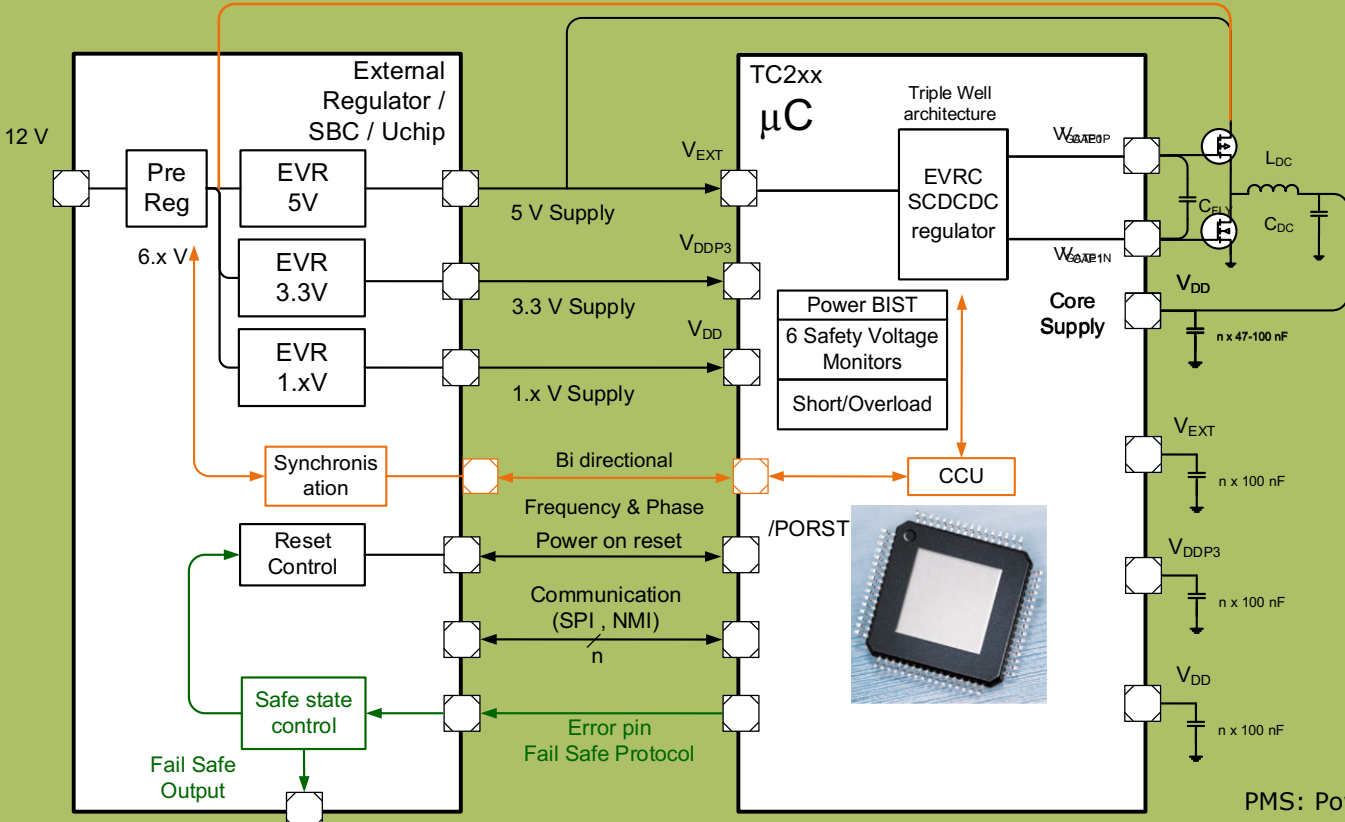
IFX Automotive Microcontroller

PMS-CE to make μC ready for on-chip DCDC (LC & SC)

1. Triple supply to Single Supply with integrated DCDC regulators devoid of power sequencing
 • ~ 50 % reduction of power supply pins and E-pad introduction

2. Safety compliant architecture :
 Error pin, Bi-directional reset and power fail, Power BIST, 6 Independent monitors..

3. DCDC Synchronization, Direct Pre-regulator drive
 • Switch capacitor distributed regulators for LE devices




PMS: Power Management System

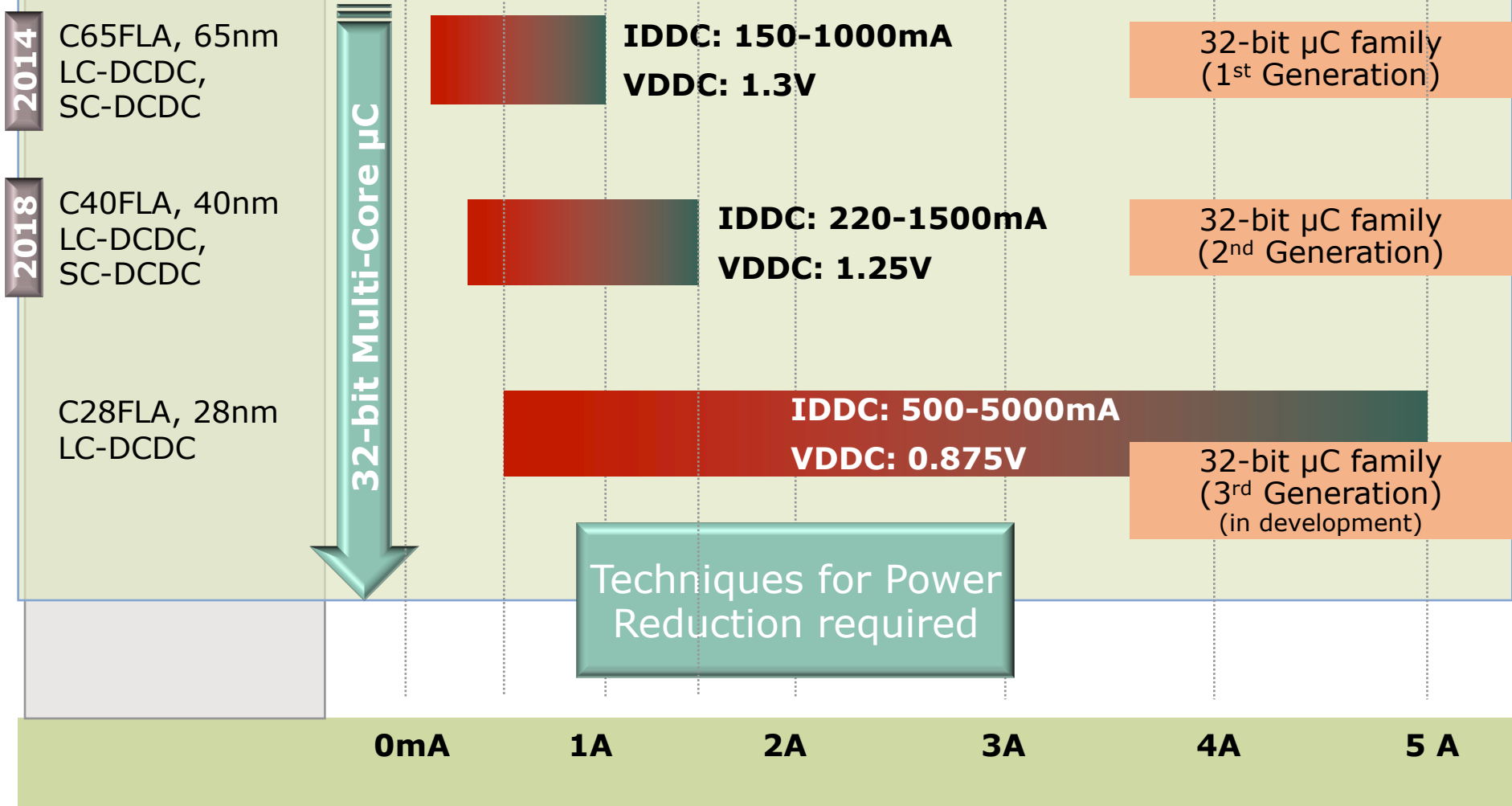
IFX Automotive Microcontroller

Supply Current Demand



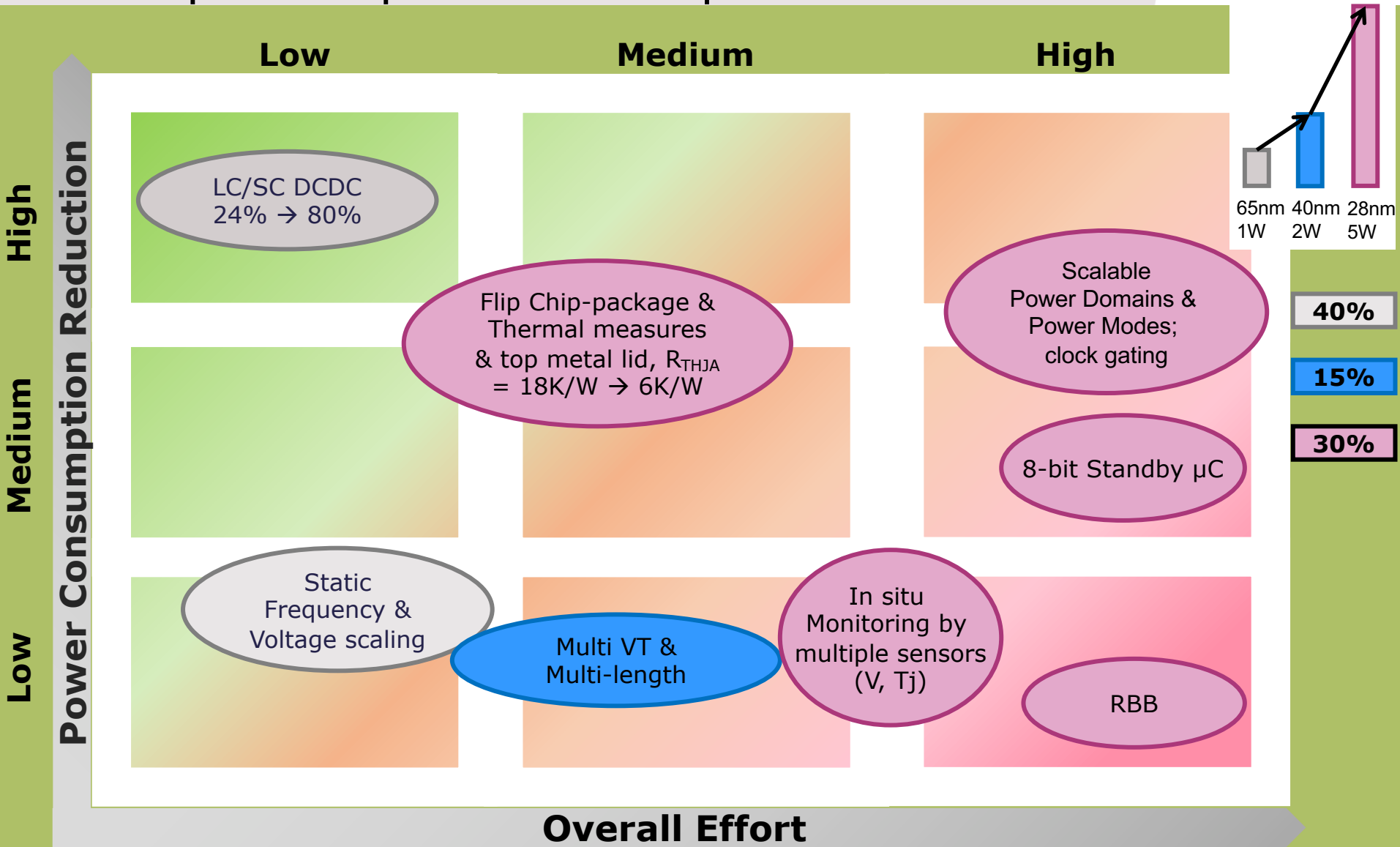
Embedded Flash
Automotive

 **LC-DCDC**
SC-DCDC



IFX Automotive Microcontroller

Techniques for power & Vdrop reduction

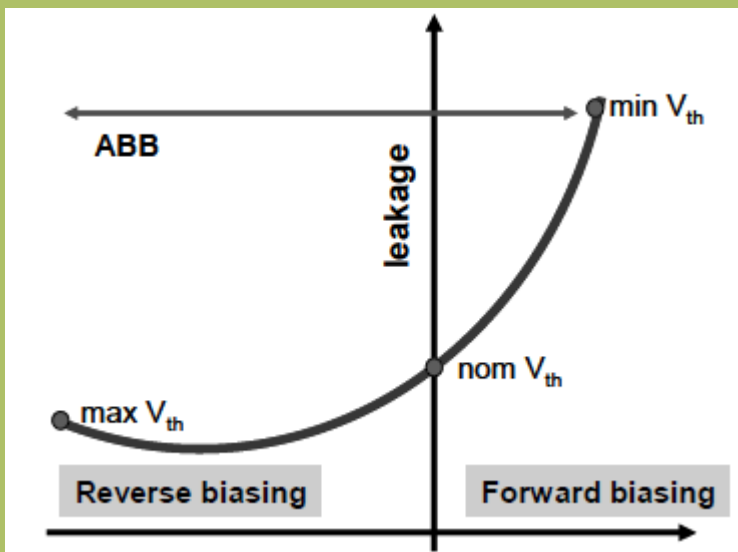


IFX Automotive Microcontroller

Development of Body Bias Test Chip, I

Transistor Body Biasing

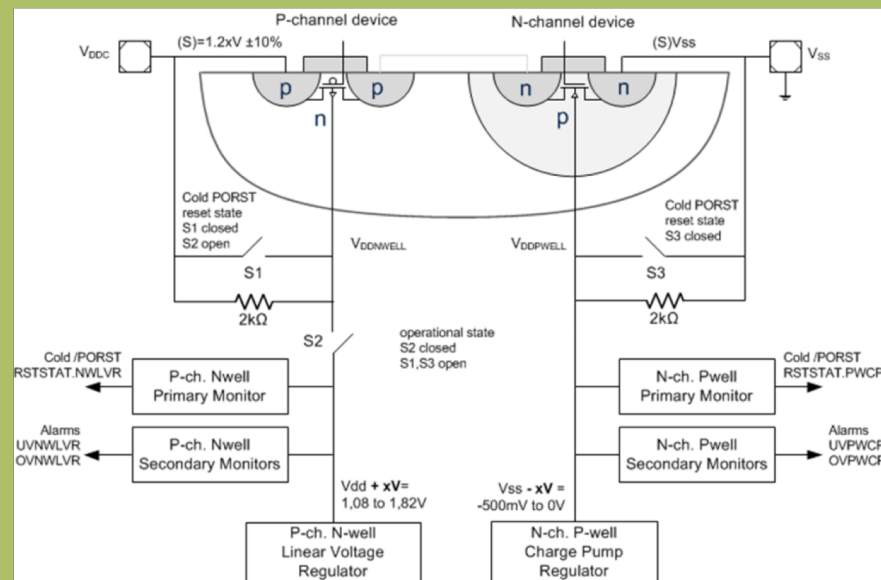
- **Investigations** for power consumption reduction by Body Bias
- **Transistor Body Bias (BB)** can be applied to adopt the threshold voltage of MOS devices



Adaptive **V**oltage **S**caling (**AVS**)
 Adaptive **B**ody **B**ias (**ABB**)

Test Chip: PMS, 40nm

- **N-well:** Linear Voltage Regulator (LVR)
- **P-well:** neg. charge pump (CP) + LVR
- **Critical** path monitoring (DUT), stop clock and scan-out in case of error

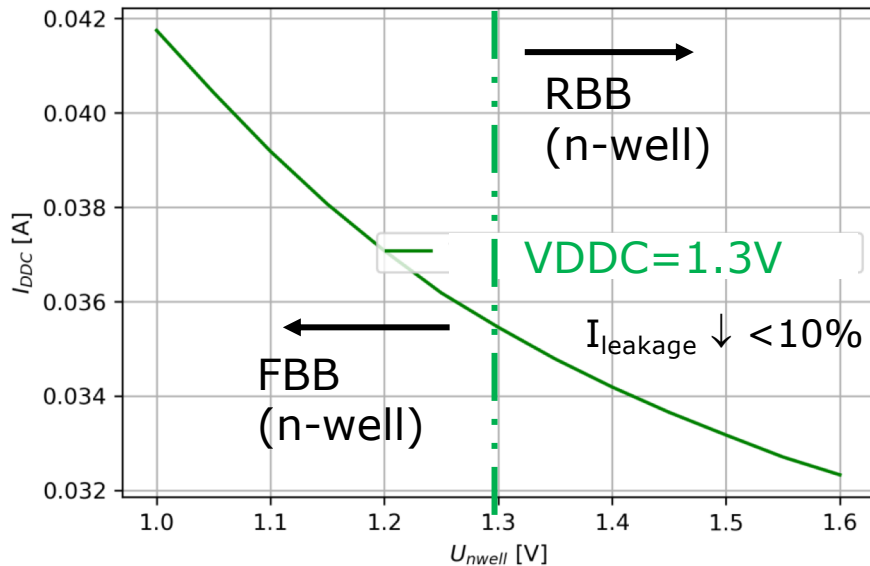


IFX Automotive Microcontroller

Development of Body Bias Test Chip, II

Test Chip: Results

- P-well=-300mV by Charge Pump
- $T_j=85^\circ\text{C}$
- Corner process (NfPf)



RBB Side Effects

- **Timing Sign off**
 - Increased Jitter, clock domain crossing (w/ & wo RBB)
- **Area penalty**
 - 0.4-1.0 mm²
- **EMC**
 - Emission \uparrow as $Cap_{filler} \downarrow$
- **Functional Safety**
 - E.g. complexity \uparrow due to well-Voltage Monitoring
- **Production Test**
 - complexity \uparrow , test time \uparrow
- **Latch Up Robustness**
 - E.g. parasitic bipolar effects

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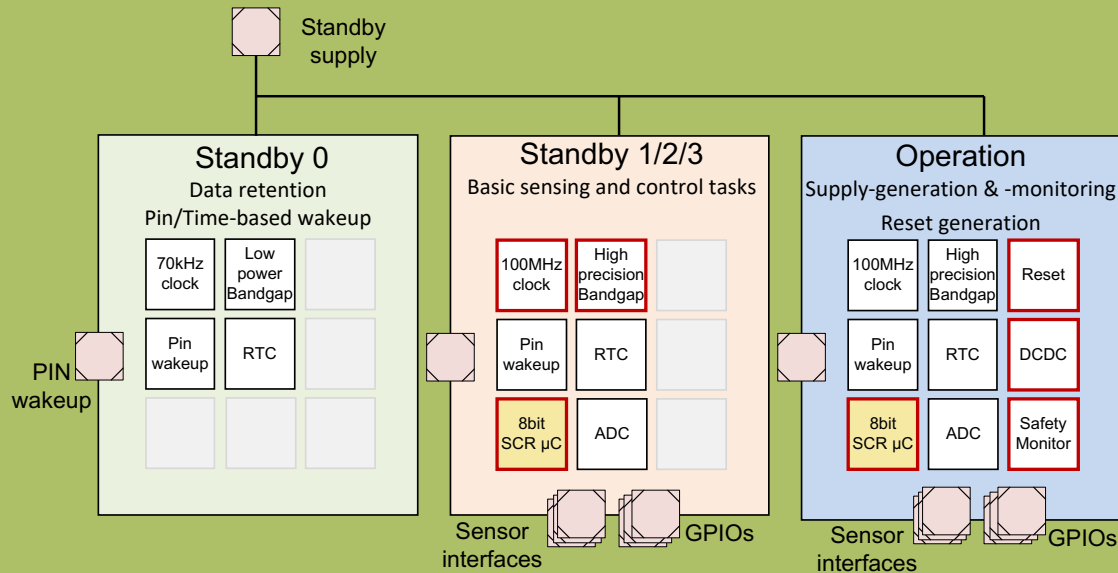
Power Management: Present Development

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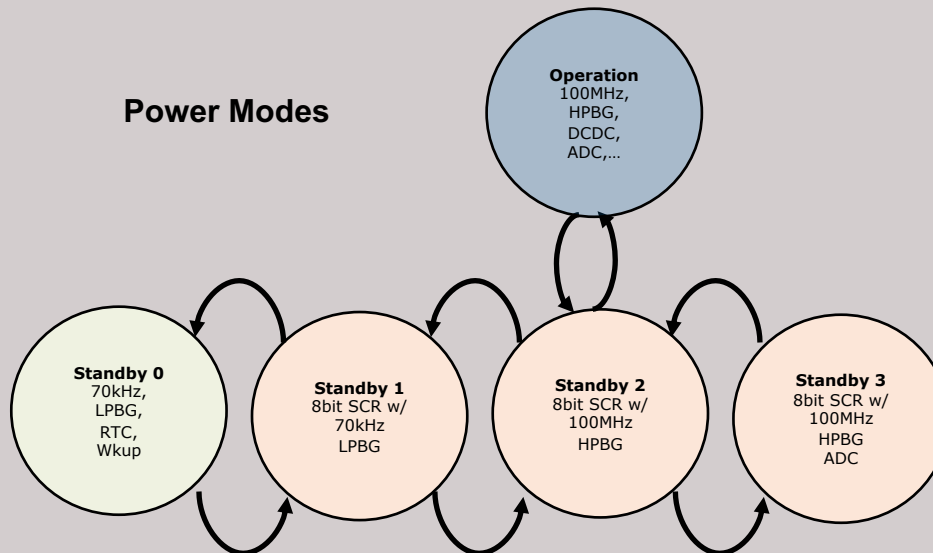
Power Management: Challenges

Power Management: Present Development

Scalable Power Domains & Power Modes;



Power Modes



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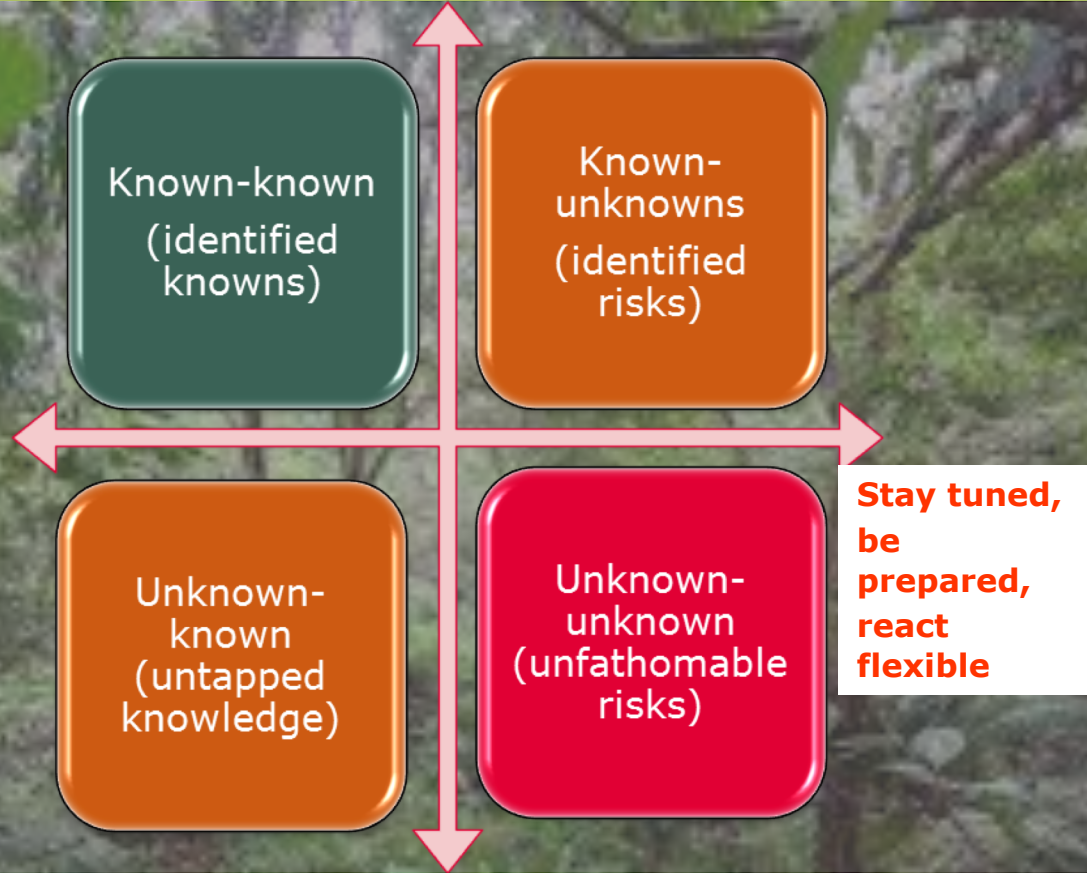
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Power Management: Challenges

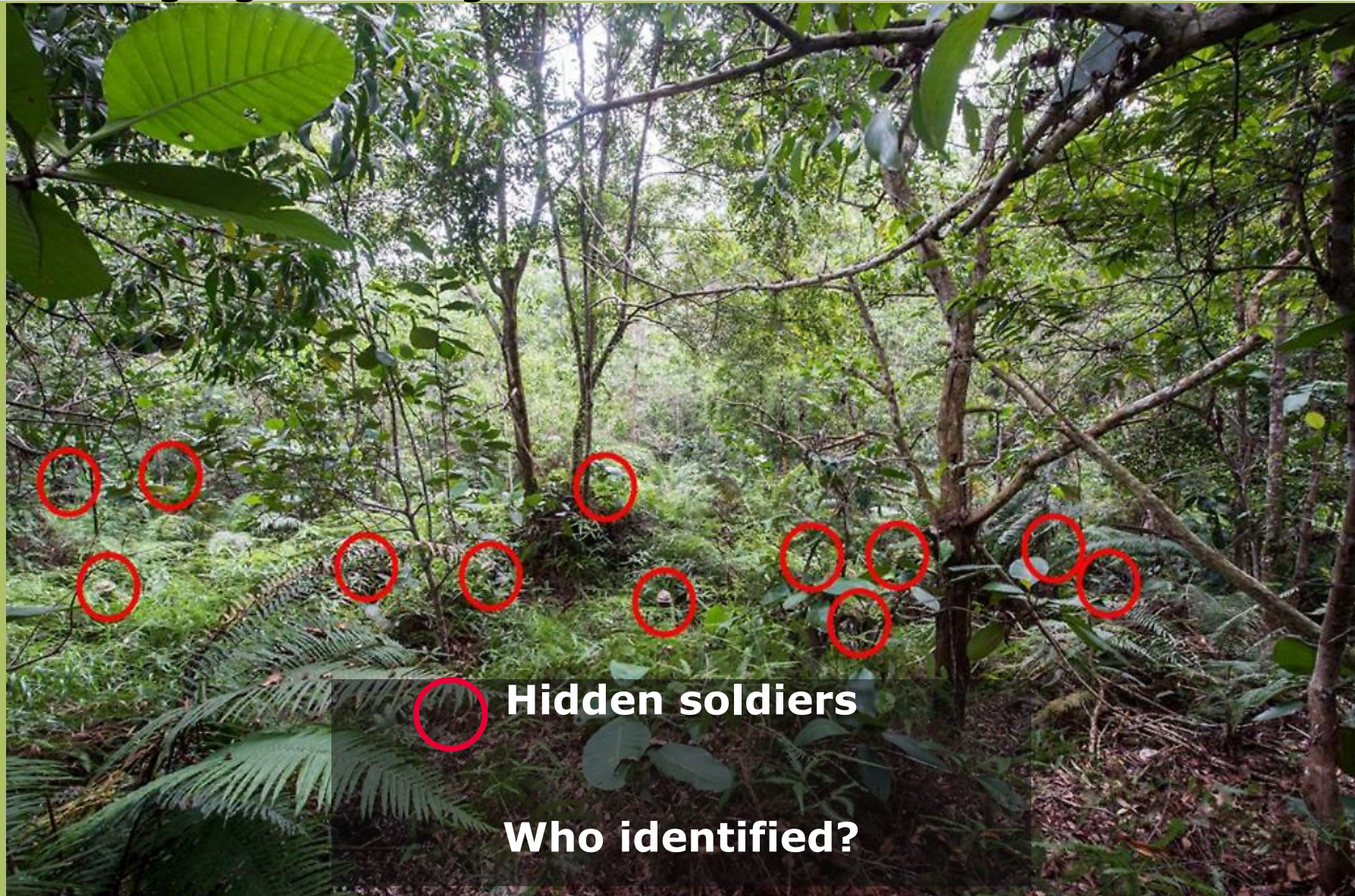
Power Management

Managing Challenges



**Challenge of concurrent engineering:
Identify risks as early as possible!!**

Power Management Managing Challenges



Hidden soldiers
Who identified?

Power Management

Managing Concurrent Engineering

Challenge

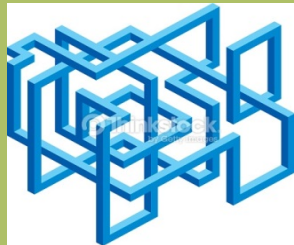
What

How



New Technology

- Leakage ?
- Matching?
- Drift effects?
- EOS
- ...



Design Complexity & Robustness

- Efficiency, Resolution
- New applications
- Cross Functional System (ana, dig)
- ...



Business Case, Time to market

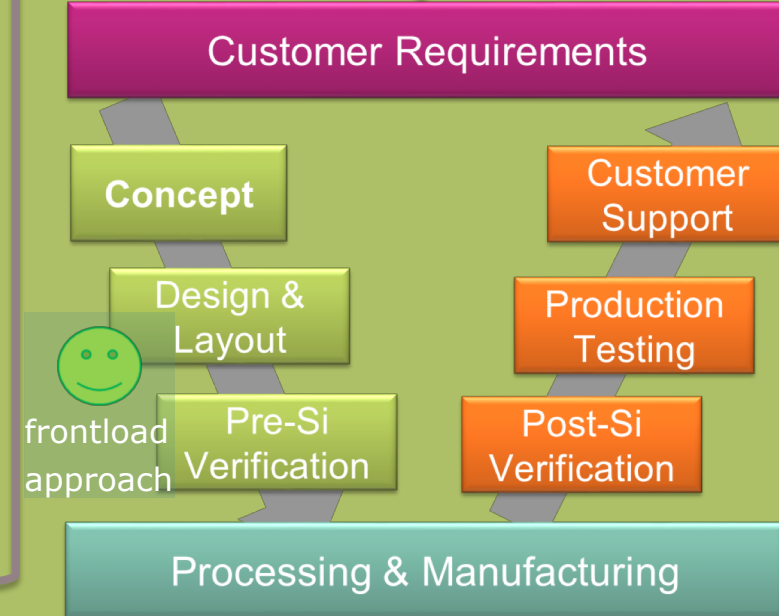
- Test time ↓
- Si area ↓
- Zero defect
- Dev. Cycle time
- ...



Physical Integration & XTALK

- Power Integrity
- Signal Integrity
- PDN
- Packaging
- ...

- **Continuously** spy for technical risks and provide solutions in time (frontloading approach)
 - Pre-development (e.g. Uni cooperation)
 - New methodologies



To the Technical Leads out there...

Avoid problems in the project , else...

Customer

Delivery delayed



Management

Business Case drops



Colleagues & Team

Focus Team or Task Force



Ex. 1) Power- & Signal Integrity (PI-SI)

XTALK issue: LC-DCDC impact on SAR ADC channels

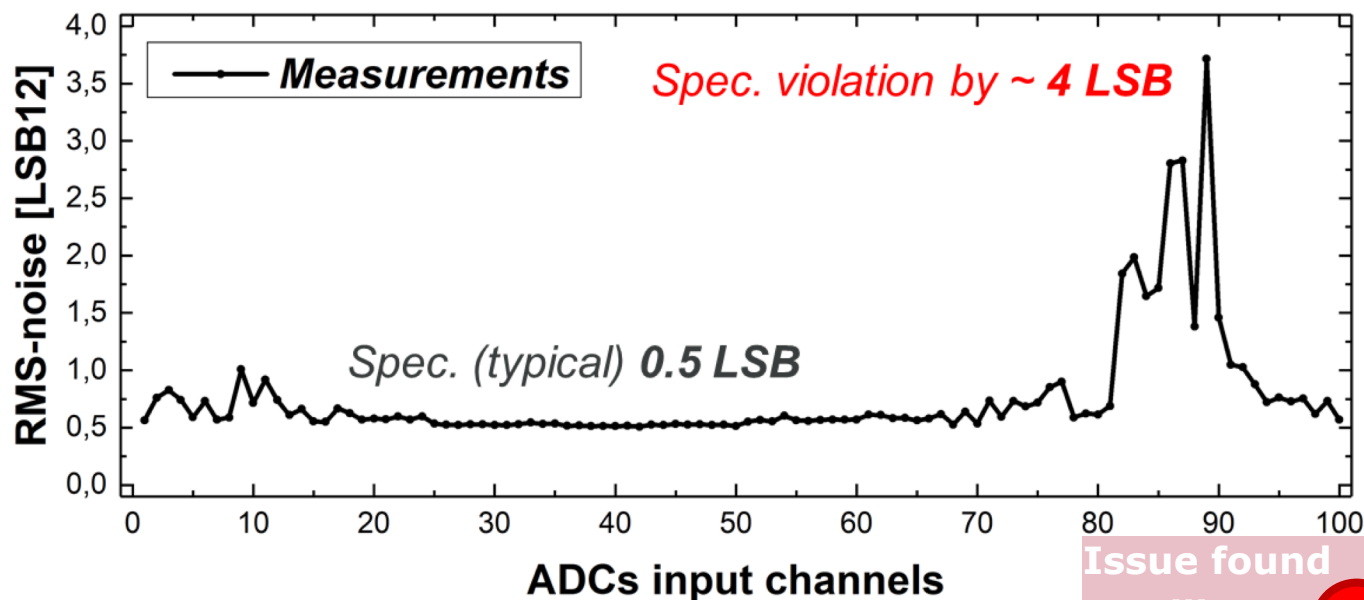
V-Model



Aggressor: DC/DC step down (buck)

Victim: Input channels of 12 bit SAR ADCs

Those ADCs experience crosstalk due to inductive coupling at package-level due to large di/dt of DC/DC gate drivers

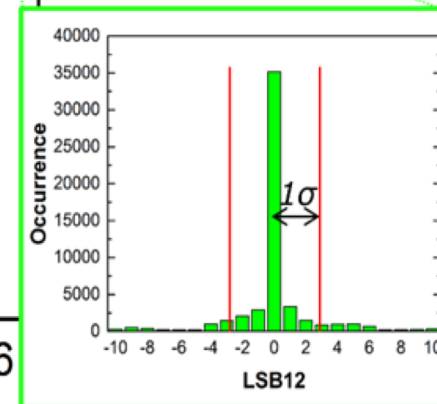
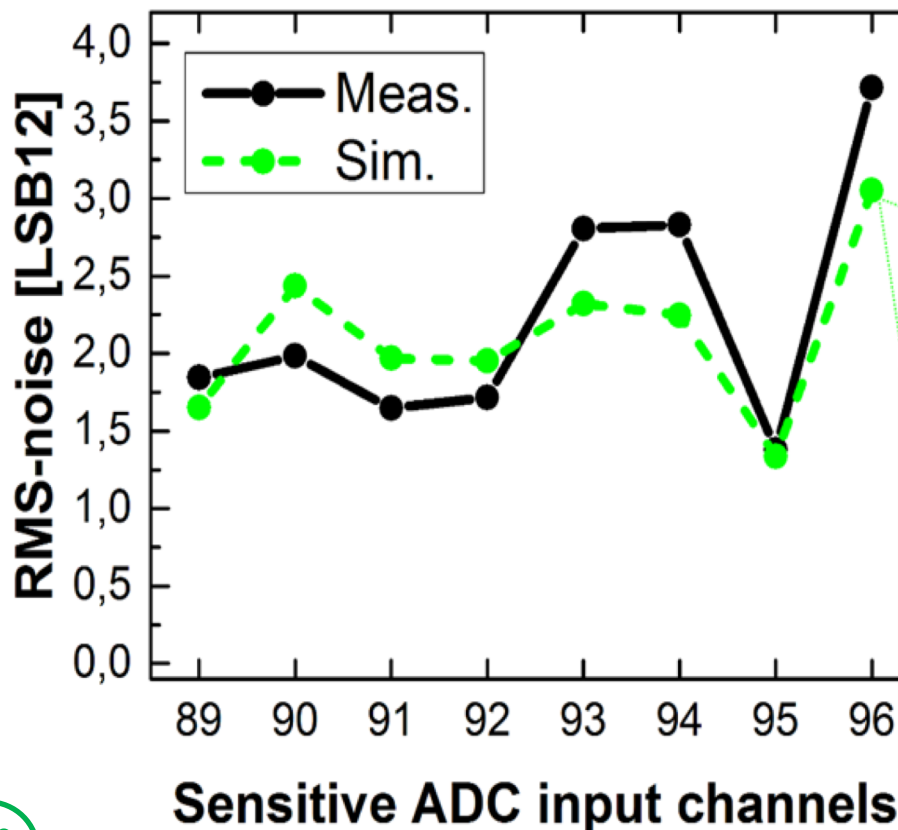
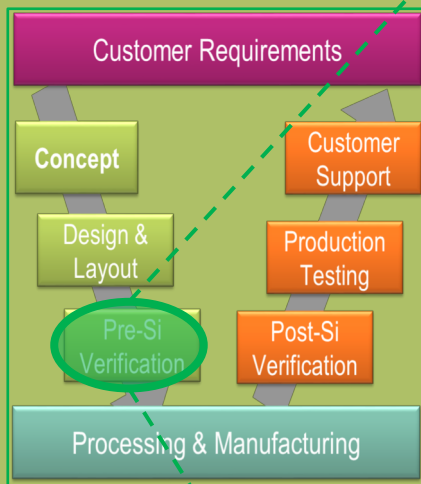


Issue found on silicon

Ex. 1) Power- & Signal Integrity (PI-SI)

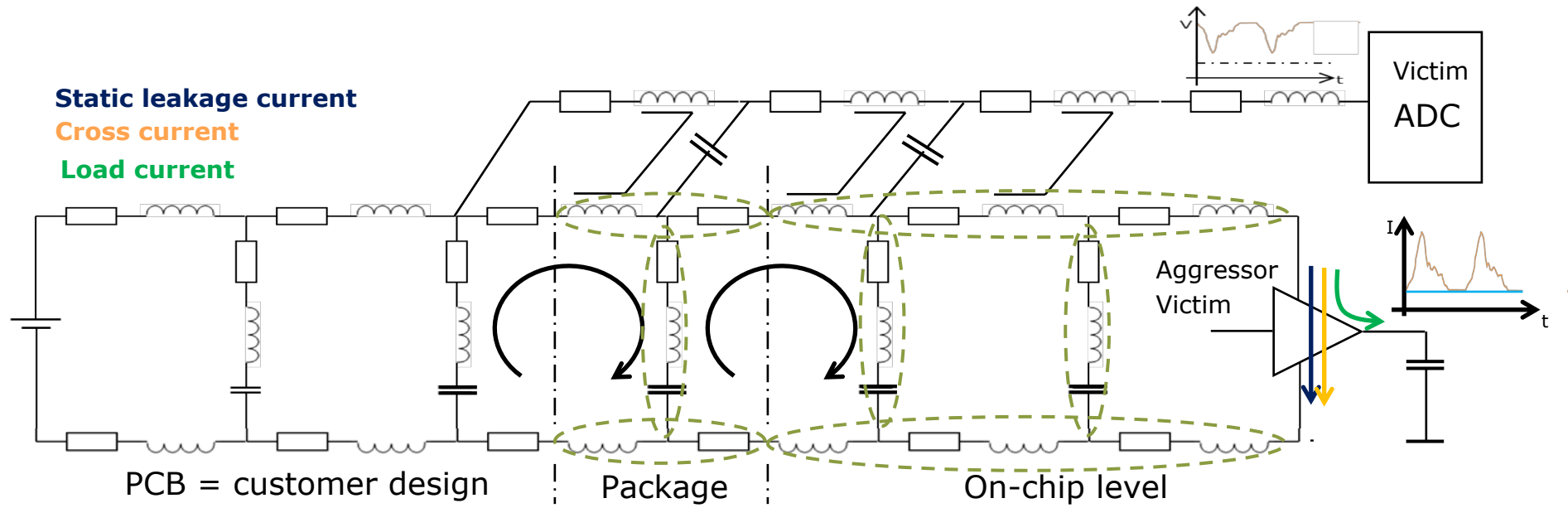
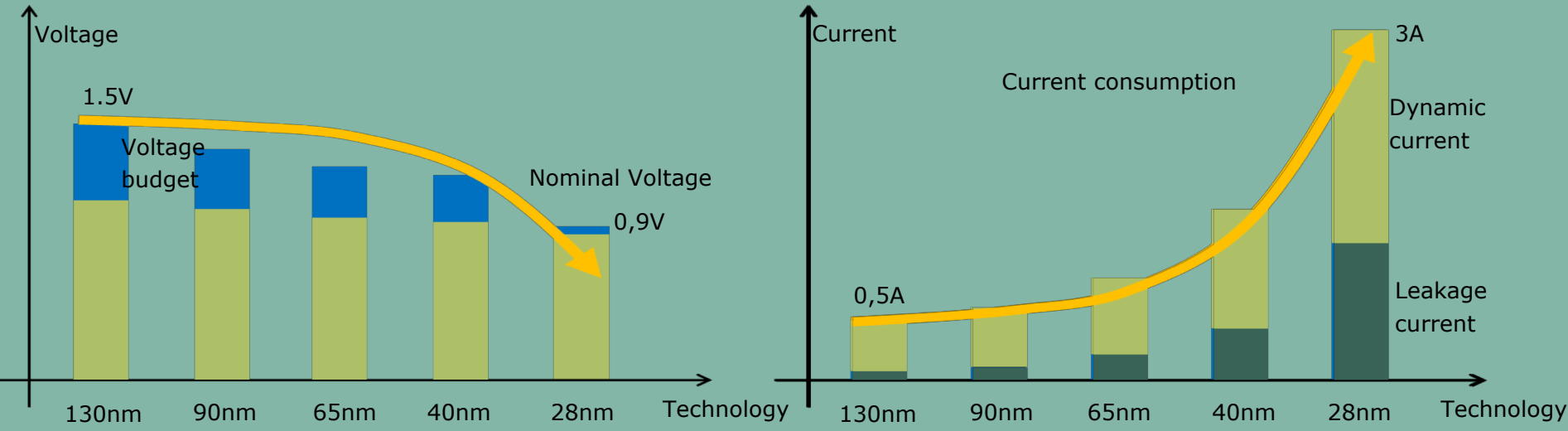
Dev. Methodology to handle XTALK effects (PCB)

V-Model



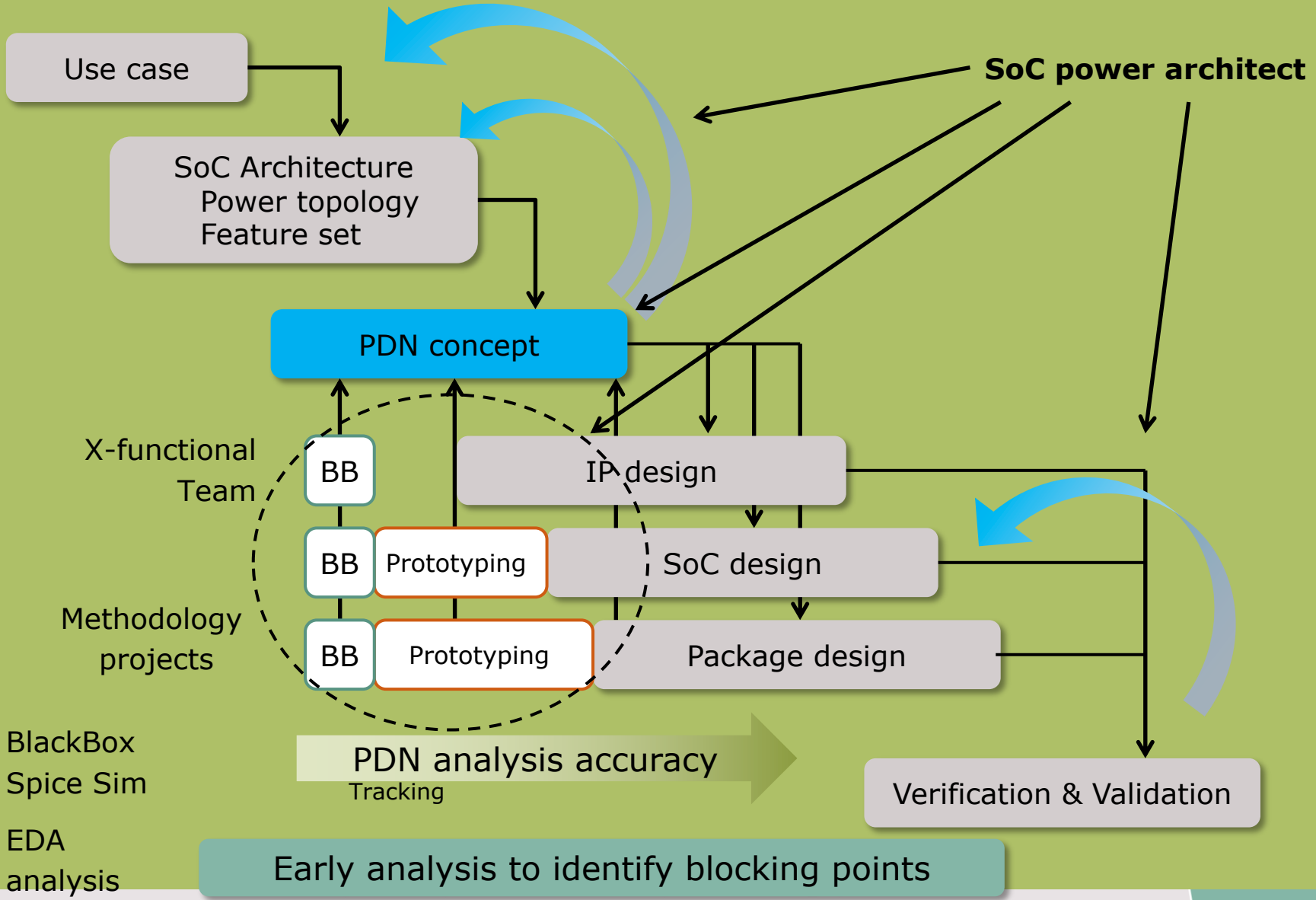
Ex. 2) Power Distribution Network

Methodology to ensure efficient PDN design



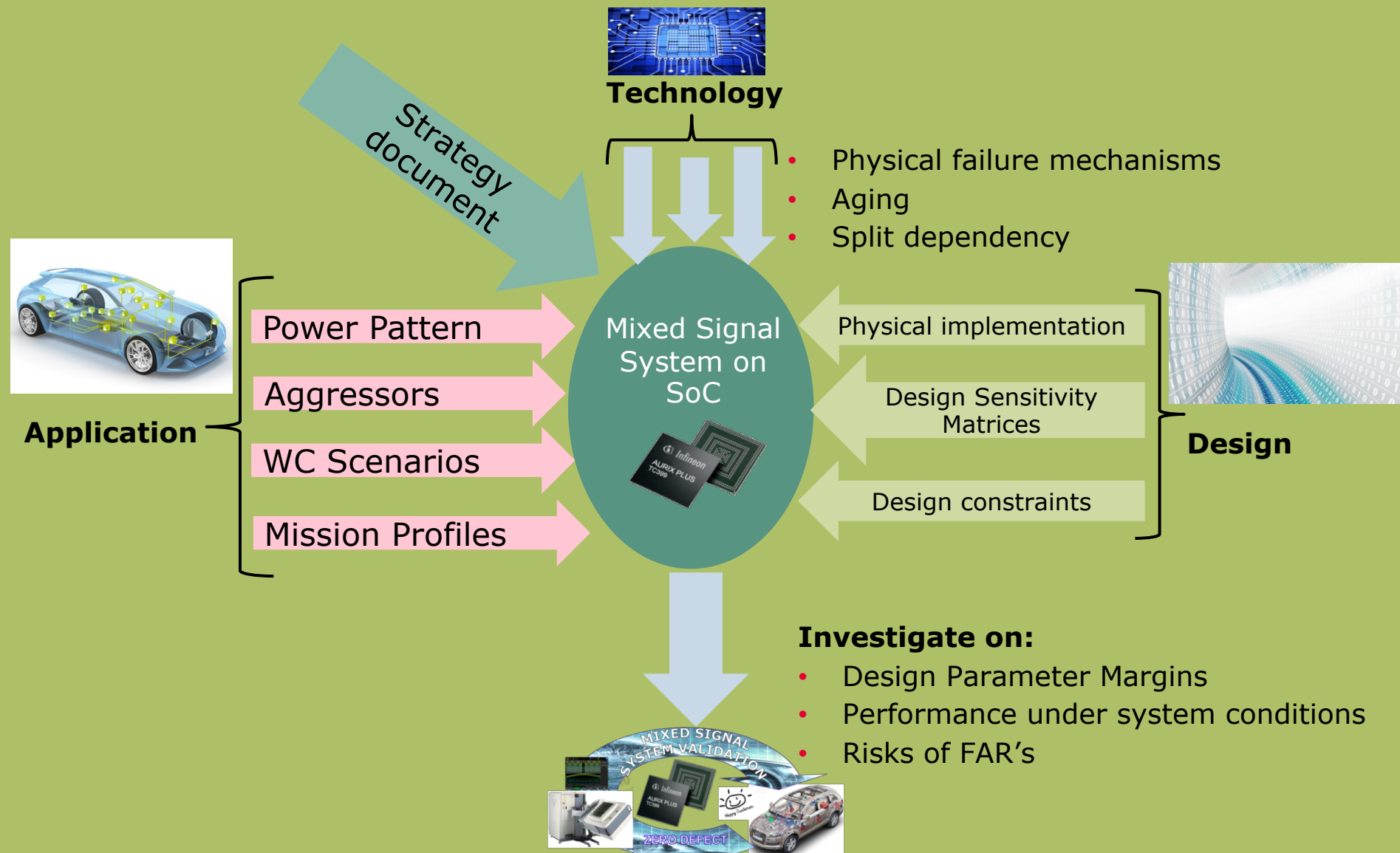
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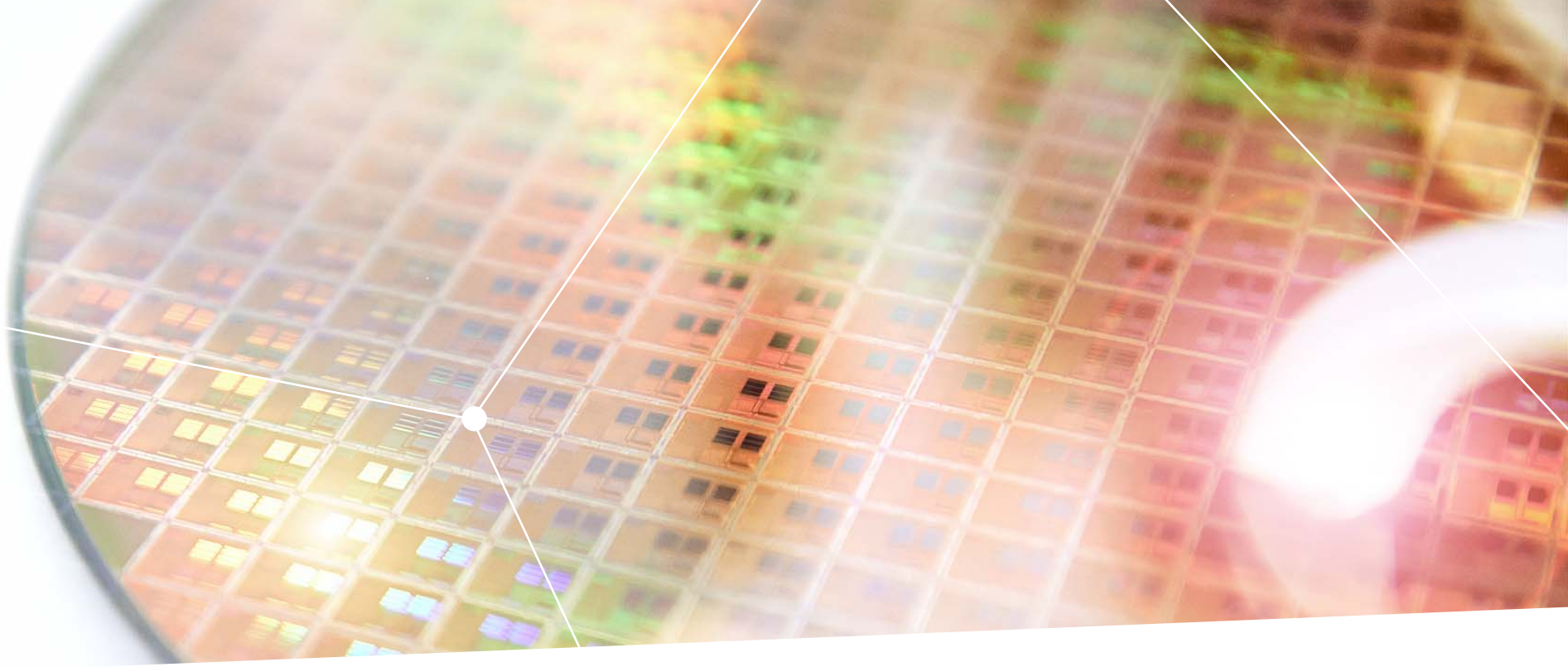
Design flow: Concurrent process



Ex. 3) Robustness Verification

Provoke field returns artificially



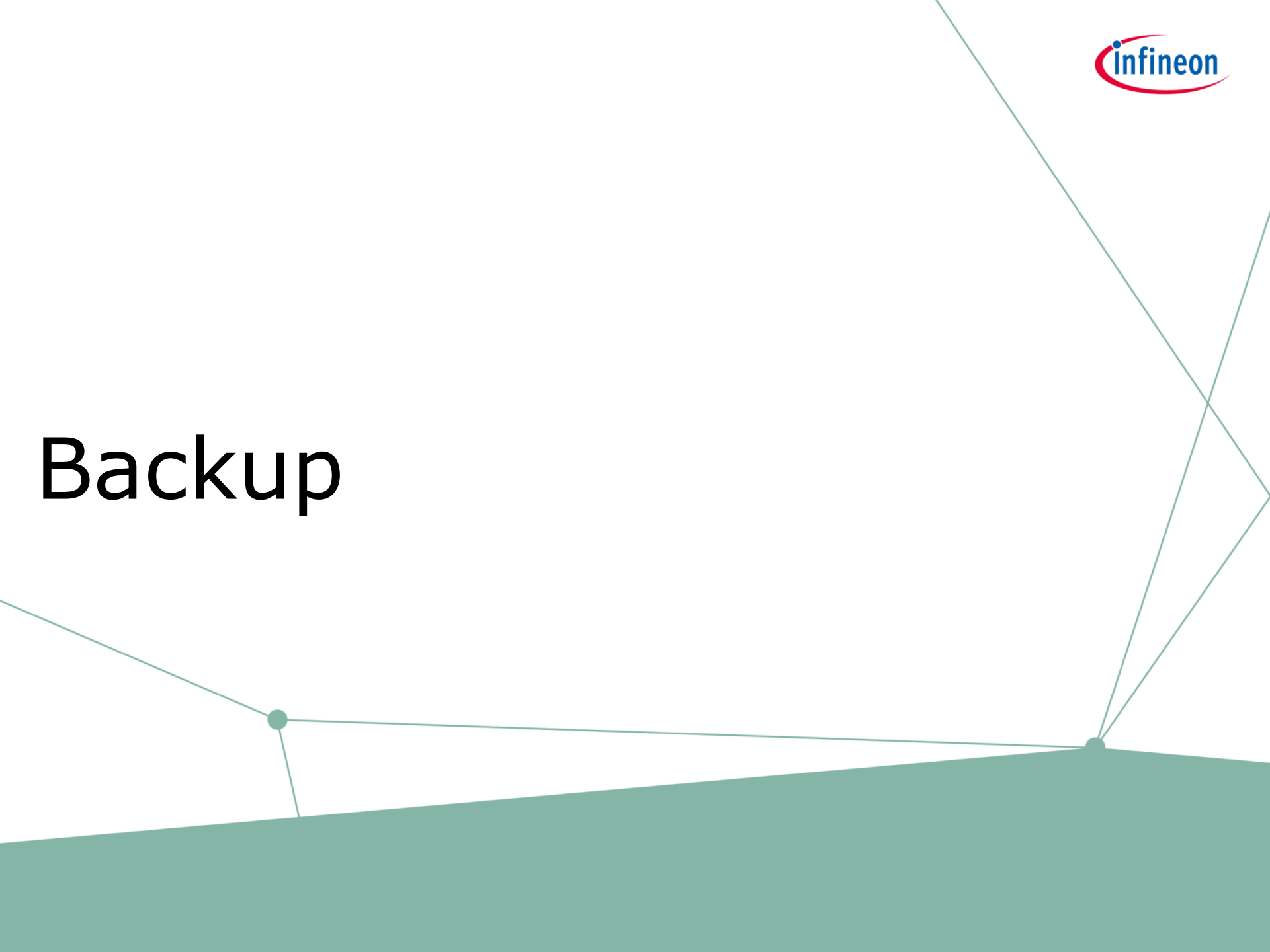


Many Thanks for your attention

Questions?



Backup





Part of your life. Part of tomorrow.

